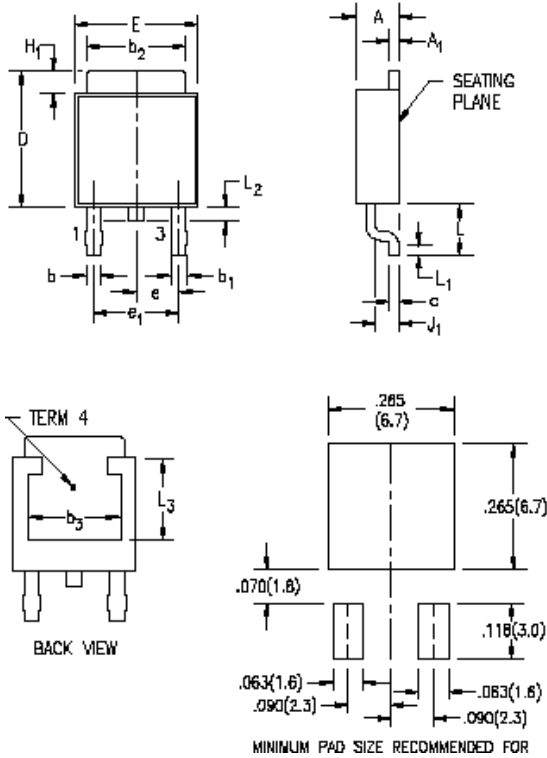




DPAK TO-252AA



TO-252AA
SURFACE MOUNT, JEDEC TO-252AA PLASTIC PACKAGE

SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	0.086	0.094	2.19	2.38	
A ₁	0.018	0.023	0.46	0.58	4,5
b	0.028	0.033	0.72	0.84	4,5
b ₁	0.033	0.045	0.84	1.14	4
b ₂	0.205	0.215	5.21	5.46	4,5
b ₃	0.190	—	4.83	—	2
c	0.018	0.023	0.46	0.58	4,5
D	0.270	0.295	6.86	7.49	
E	0.250	0.265	6.35	6.73	
e	0.090 TYP.		2.28 TYP.		7
e ₁	0.180 BSC		4.57 BSC		7
H ₁	0.035	0.050	0.89	1.27	
J ₁	0.040	0.045	1.02	1.14	
L	0.100	0.115	2.54	2.92	
L ₁	0.020	—	0.51	—	4,6
L ₂	0.025	0.040	0.64	1.01	3
L ₃	0.170	—	4.32	—	2

NOTES:

- These dimensions are within allowable dimensions of Rev. B of JEDEC TO-252AA outline dated 9-88.
- L₃ and b₃ dimensions establish a minimum mounting surface for terminal 4.
- Solder finish uncontrolled in this area.
- Dimension (without solder).
- Add typically 0.002 inches (0.05mm) for solder plating.
- L₁ is the terminal length for soldering.
- Position of lead to be measured 0.090 inches (2.28mm) from bottom of dimension D.
- Controlling dimension: Inch.
- Revision 10 dated 11-Apr-00.

